

P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)			
- 20	0.184 at V _{GS} = - 4.5 V	- 0.94	4.23			
- 20	0.268 at V _{GS} = - 2.5 V	- 0.78	4.20			

FEATURES

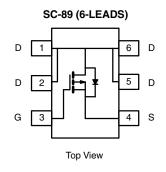
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_q Tested
- Compliant to RoHS Directive 2002/95/EC

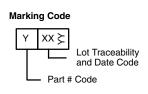


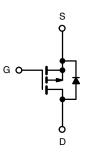
ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

• Load Switch for Portable Devices







Ordering Information: Si1069X-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	- 20	V		
Gate-Source Voltage		V _{GS}	± 12	v		
Continuous Drain Current (T _{.I} = 150 °C)	T _A = 25 °C	1-	- 0.94 ^{b, c}			
Continuous Diam Current (1) = 150 C)	T _A = 70 °C	I _D	- 0.75 ^{b, c}	Α		
Pulsed Drain Current		I _{DM}	- 8			
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 0.2 ^{b, c}			
Maniana Banas Bissis stand	T _A = 25 °C	P _D	0.236 ^{b, c}	w		
Maximum Power Dissipation ^a	T _A = 70 °C		0.151 ^{b, c}			
Operating Junction and Storage Temperature Ra	nge	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
AA:' ht' t At-'ta h	t ≤ 5 s	R _{thJA}	440	530	°C/W		
Maximum Junction-to-Ambient ^{a, b}	Steady State		540	650			

Notes:

- a. Based on $T_A = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 16.7		m\//°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 _D = - 250 μΑ		2.95		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.6		- 1.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zava Cata Valtaga Drain Current	I	V _{DS} = - 20 V, V _{GS} = 0 V			- 1	μΑ	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 85 °C			- 10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 8			Α	
D : 0	D	V _{GS} = - 4.5 V, I _D = - 0.94 A		0.153	0.184		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 0.78 A		0.218	0.268	Ω	
Forward Transconductance	9 _{fs}	V _{DS} = - 10 V, I _D = - 0.94 A		4		S	
Dynamic ^b					•	•	
Input Capacitance	C _{iss}			308		pF	
Output Capacitance	C _{oss}	V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz		78			
Reverse Transfer Capacitance	C _{rss}			59			
Total Cata Charge	0	$V_{DS} = -10 \text{ V}, V_{GS} = -5 \text{ V}, I_D = -0.94 \text{ A}$		4.57	6.86		
Total Gate Charge	Q_g			4.23	6.35	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -0.94 \text{ A}$		0.71			
Gate-Drain Charge	Q _{gd}			1.67		1	
Gate Resistance	R _g	f = 1 MHz		9	13.5	Ω	
Turn-On Delay Time	t _{d(on)}			19	28.5		
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_{L} = 13.3 \Omega$		31	47	ns	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -0.75 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		23	34.5		
Fall Time	t _f			7	10.5		
Drain-Source Body Diode Characteris	stics						
Pulse Diode Forward Current ^a	I _{SM}				8	Α	
Body Diode Voltage	V _{SD}	I _S = - 0.64 A		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			19	28.5	nC	
Body Diode Reverse Recovery Charge		I _E = - 0.64 A, dI/dt = 100 A/μs		6.65	10		
Reverse Recovery Fall Time	ta	i _F = - 0.04 A, αί/αι = 100 A/μs		7		ns	
Reverse Recovery Rise Time	t _b			12		1	

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

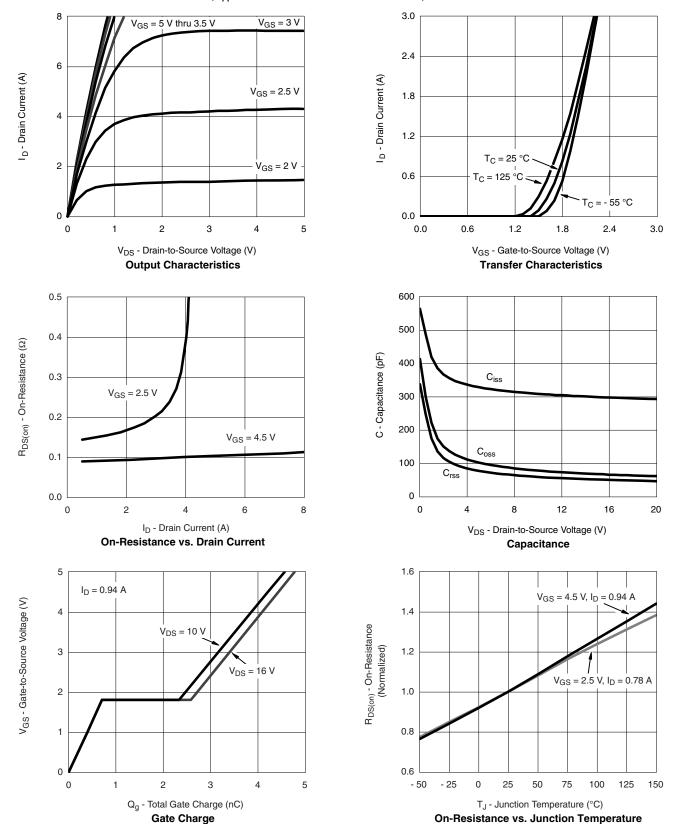
b. Guaranteed by design, not subject to production testing.







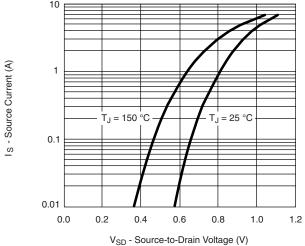
TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)



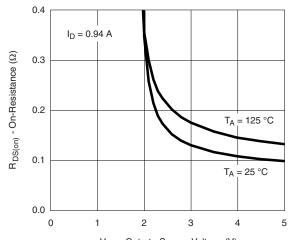
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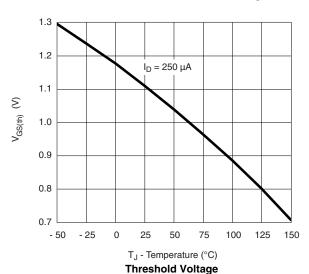
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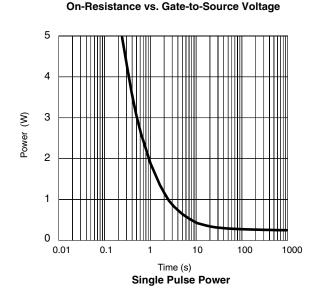


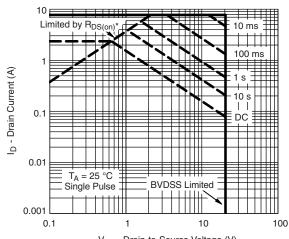
Source-Drain Diode Forward Voltage



V_{GS} - Gate-to-Source Voltage (V)







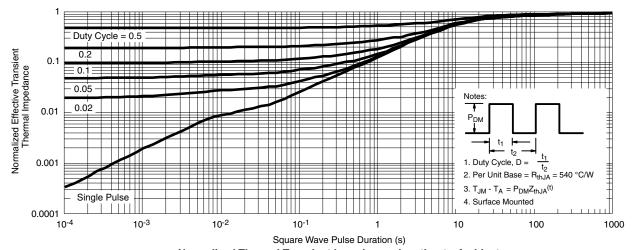
 $V_{DS} \mbox{ - Drain-to-Source Voltage (V)} \\ ^* \mbox{ V}_{GS} \mbox{ > minimum V}_{GS} \mbox{ at which } R_{DS(on)} \mbox{ is specified}$

Safe Operating Area, Junction-to-Ambient





TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)



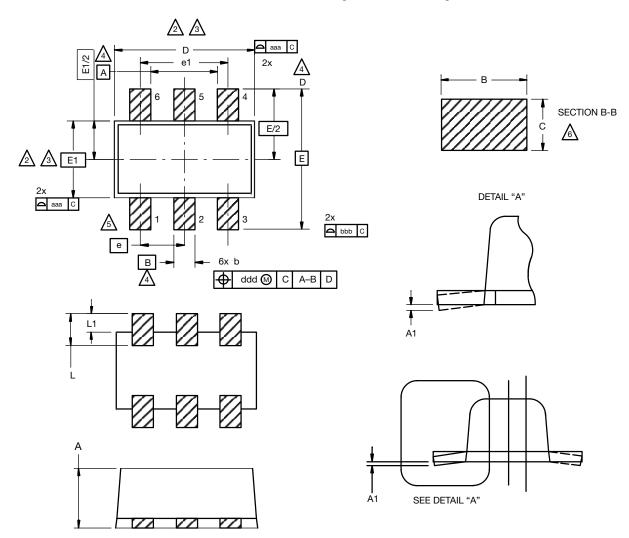
Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppq?70442.

Document Number: 70442 S19-0207-Rev. D, 04-Mar-2019



SC-89 6-Leads (SOT-563F)



Notes

1. Dimensions in millimeters.

Dimension D does not include mold flash, protrusions or gate burrs. Mold flush, protrusions or gate burrs shall not exceed 0.15 mm per dimension E1 does not include interlead flash or protrusion, interlead flash or protrusion shall not exceed 0.15 mm per side.

Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, the bar burrs, gate burrs and interlead flash, but including any mismatch between the top and the bottom of the plastic body.

ADatums A, B and D to be determined 0.10 mm from the lead tip.

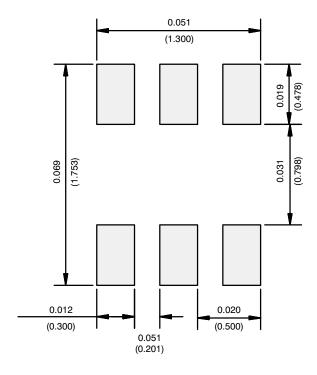
A Terminal numbers are shown for reference only.

These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIM.	MILLIMETERS				
Dilvi.	MIN.	NOM.	MAX.		
Α	0.56	0.58	0.60		
A1	0	0.02	0.10		
b	0.15	0.22	0.30		
С	0.10	0.14	0.18		
D	1.50	1.60	1.70		
Е	1.50	1.60	1.70		
E1	1.15	1.20	1.25		
е	0.45	0.50	0.55		
e1	0.95	1.00	1.05		
L	0.25	0.35	0.50		
L1	0.10	0.20	0.30		
C14-0439-Rev. C, 11-Aug-14 DWG: 5880					



RECOMMENDED MINIMUM PADS FOR SC-89: 6-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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